MEMS packaging

Abstrak

This book discusses the prevalent practices and enabling techniques in the assembly, packaging and testing of microelectromechanical systems (MEMS). The entire spectrum of assembly, packaging and testing of MEMS and microsystems, from essential enabling technologies to applications in key industries of life sciences, telecommunications and aerospace engineering is covered. Other topics covered include the bonding and sealing of microcomponents, the process flow of MEMS and microsystem packaging, automated microassembly, and testing and design for testing.